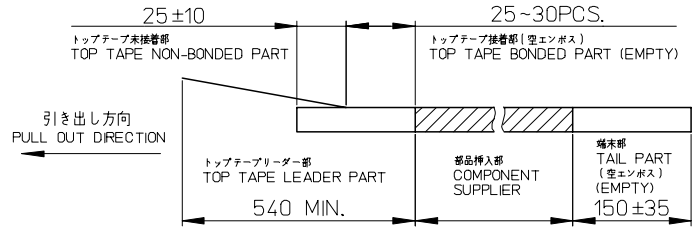


エンボステープ内の製品の向き  
DIRECTION OF PRODUCT  
IN EMBOSSED TAPE  
(SCALE:2-1)

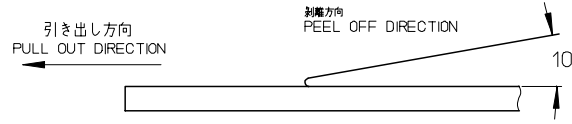
①	コネクタ CONNECTOR
②	エンボステープ EMBOSSED TAPE
③	トップテープ TOP TAPE
④	リール REEL

注記

- コネクタ詳細は SD-51387-006を参照下さい。  
REFER TO SD-51387-006
- 梱包数量: 1200個/リール  
NUMBER OF CONNECTOR : 1200 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度:  $0.6 \pm 0.35N$  ( $60 \pm 35gf$ )  
<剥離速度: 300mm/min (参考)> (剥離方向は下図参照)  
PEEL-OFF FORCE OF TOP TAPE :  $0.6 \pm 0.35N$  ( $60 \pm 35gf$ )  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
<PEEL-OFF SPEED : 300mm/min (REF.)>



- 材料  
MATERIAL  
キャリアテープ: ポリプロピレン  
CARRIER TAPE : POLYPROPYLENE  
トップテープ : ポリエステル, ポリエチレン  
TOP TAPE : POLYESTER, POLYETHYLENE  
リール : ポリスチレン  
REEL : POLYSTYREN

51387-0530	51387-***0
製品番号 MATERIAL No.	MODEL No.

新編作成 EC NO: J2005-0570 DRAWN: MSHINYAMA 2004/08/30 CHKD: HTAKASE 2004/08/30 APPR: JMIYAZAW 2004/09/02 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MSHINYAMA	DATE 04/07/18	TITLE EMBOSSED TAPE PKG. FOR 51387-0539 -LEAD FREE-		
	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/07/18	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY JMIYAZAWA	DATE 04/07/18	DOCUMENT NO. SD-51387-005	SHEET NO. 1 OF 1	
	ANGULAR	± 3 °	MATERIAL NO. SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F

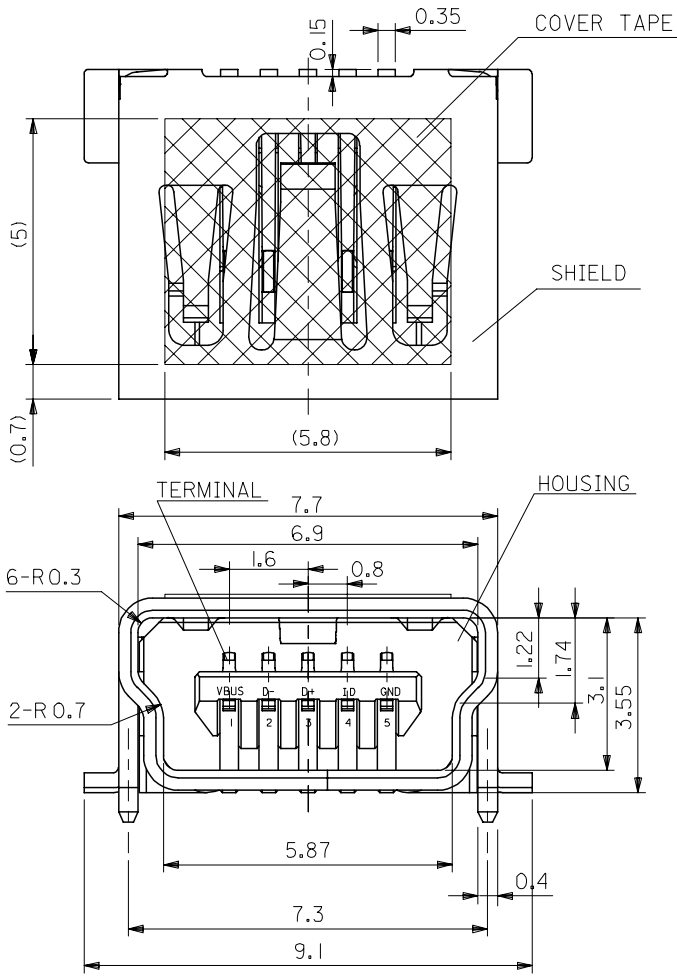
E

D

C

B

A



注記  
NOTES

1. 材質

MATERIAL

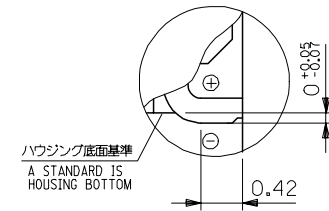
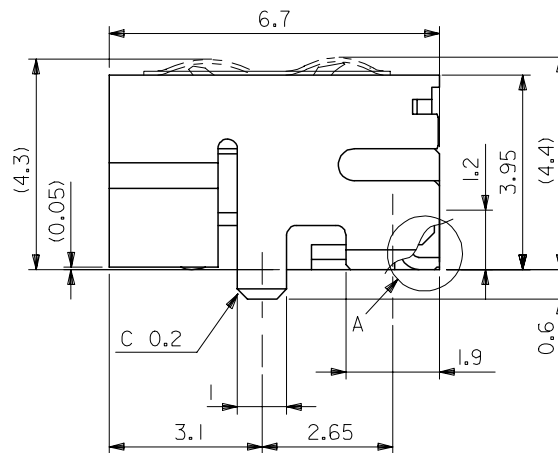
ハウジング: 耐熱樹脂 ガラス充填, 黒色, UL94V-0  
 HOUSING: HEAT RESISTANT PLASTIC,  
 GLASS FILLED, BLACK, UL94V-0  
 ターミナル: 銅合金 (t=0.25)  
 TERMINAL: COPPER ALLOY (t=0.25)  
 シールド: 銅合金 (t=0.4)  
 SHIELD: COPPER ALLOY (t=0.4)  
 カバー テープ: ポリイミド (t=0.08)  
 COVER TAPE: POLYIMIDE (t=0.08)

2. メッキ仕様

PLATING

ターミナル 接点部: 金メッキ  
 TERMINAL CONTACT AREA: GOLD  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地部: ニッケルメッキ  
 UNDER PLATING: NICKEL  
 シールド: 錫メッキ  
 SHIELD: TIN  
 下地部: ニッケル  
 UNDER PLATING: NICKEL

3. 平坦度は0.1mm MAX.  
 COPLANARITY 0.1mm MAX.



5	51387-0539
極数 CKT.	製品番号 MATERIAL NO.

REVISED EC NO: J2007-2931 DRWN: AYOYAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APP: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006			
	ANGULAR	±3 °	MATERIAL NO.		SHEET NO. 1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F

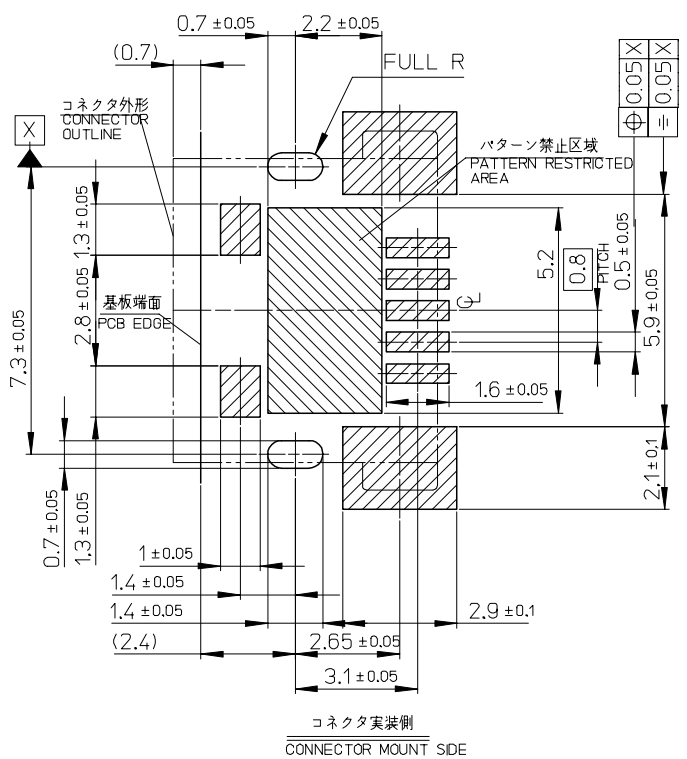
E

D

C

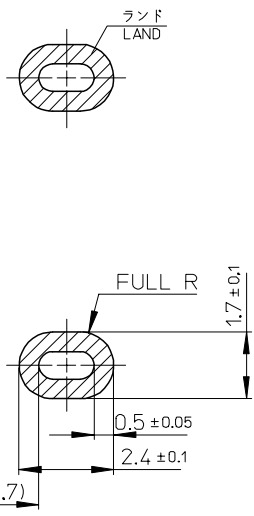
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A

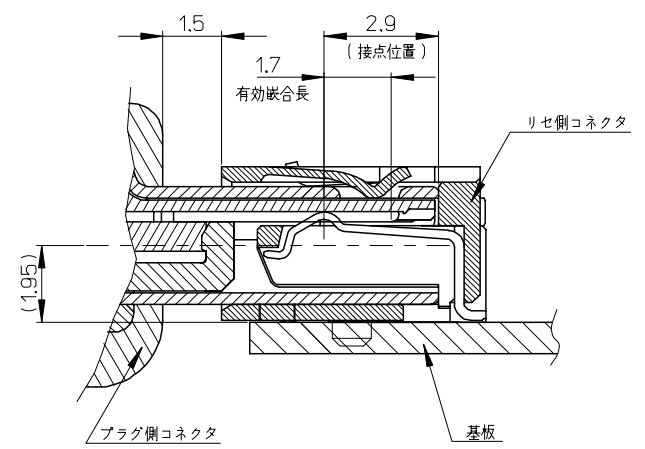


コネクタ実装側  
CONNECTOR MOUNT SIDE

推奨基板寸法 (SCALE 8:1)  
RECOMMENDED PCB PATTERN LAYOUT



逆側  
REVERSE SIDE



コネクタ嵌合図  
(SCALE 8:1)

REVISED EC NO: J2007-2931 DRWN: A0YAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	MATERIAL NO. SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				